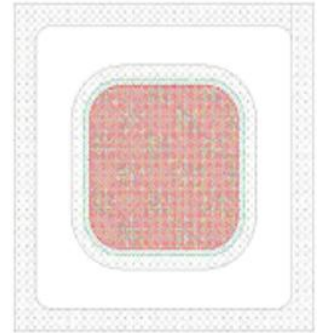
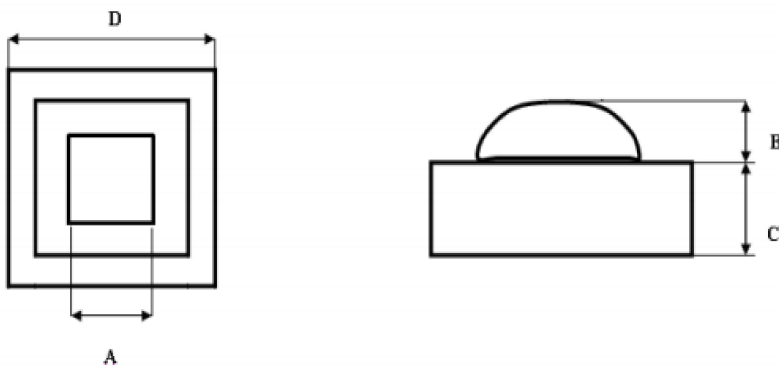


**Features**

- Epitaxial Zener Chip
- Suitable for glass-tube package.
- Plating metal: Back side:Ag, Top side: Ag ball
- Die size: 0.32mm\*0.32mm
- Die thickness: 140mil
- Wafer size: 5", PDPW: 108,000die/wafer



**Chip outline**



Parameter	Symbol	Min. Value	Typical Value	Max. Value	Unit
ChIP size	D	280		300	uM
chip thickness	C	120		160	uM
Silver ball size	A	196		240	uM
Silver ball height	B	20		55	uM
Street size	/		40		uM

**MAXIMUM RATINGS**

Parameter	Symbol	Test Condition	Value	Unit
Operating temperature	$T_J$		175	°C
Storage temperature	$T_{STG}$		-50~+175	°C

Electrical Characteristics ((Rating at 25°C ambient, refer to the Finished Goods)

( $V_F < 1.0V @ I_F = 100mA$ )

Part No.	$V_Z @ I_Z = 5mA$		Max. Zener impedance		Max.Reverse leakage current @ $V_R$	
	Min.	Max.	$Z_{ZK}(\Omega) @ I_{ZK} = 1mA$	$Z_{ZK}(\Omega) @ I_{ZK} = 5mA$	$I_R(\mu A)$	$V_R(V)$
GDZ2CW032150YQ-2S	14.7	15.3	110	30	0.1	11